Week 9 Report

This week I finished the Printed Circuit Board for our senior design project. I placed all of the parts for the main gain stage of the amplifier circuit. All the leads for the main gain stage are made extra large to accommodate the high level of current that will be flowing through them. The lead size used was 0.6 in. I placed all the parts for the pre-driver circuit, the pin driver. The pin driver has a surface part and the leads are 0.3 in. I placed the part for the microprocessor but I still need to have the finished pin out for the microprocessor to finish laying down the leads.

I also made another transducer mold. The previous mold was dissolved in 6 normal hydrochloric acid by accident by me while trying to clean it from polyethylene while trying to work with plastics for the covering. The new mold has a semi-spherical dome shape so that the transducers made from it will have a 1.0 in radius to it.
Figure 1. PCB
Figure 2. New pellet press without dome shape.